

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC9502xxxxAR-G

Typical Mass: 25 mg

| Part name | Weight(mg) | Material name | Ratio(ppm) | CAS number |
|--------------|------------|---------------|------------|------------|
| Silicon chip | 1.492 | Silicon | 59700 | 7440-21-3 |
| | - | Arsenic | 3 | 7440-38-2 |
| Leadframe | 10.091 | Copper | 403600 | 7440-50-8 |
| | 0.025 | Tin | 1000 | 7440-31-5 |
| | 0.022 | Zinc | 900 | 7440-66-6 |
| | 0.025 | Chromium | 1000 | 7440-47-3 |
| | 0.556 | Silver | 22200 | 7440-22-4 |
| Die attach | 0.027 | Silver | 1100 | 7440-22-4 |
| | 0.009 | Epoxy | 400 | — |
| Bonding wire | 0.100 | Gold | 4000 | 7440-57-5 |
| | | | | |
| Resin | 10.144 | Silica | 405800 | 60676-86-0 |
| | 0.754 | Epoxy Resin | 30100 | — |
| | 0.696 | Phenol Resin | 27800 | — |
| Plating | 1.058 | Tin | 42300 | 7440-31-5 |
| | | | | |

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."